

## N-Channel Super Junction Power MOSFET III

### General Description

The series of devices use advanced super junction technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

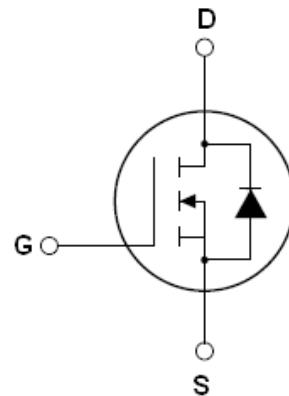
### Features

- New technology for high voltage device
- Low on-resistance and low conduction losses
- Small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

### Application

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

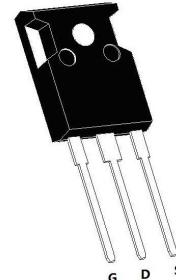
$V_{DS}$	650	V
$R_{DS(ON)} \text{ TYP.}$	36	$\text{m}\Omega$
$I_D$	75	A



Schematic diagram

### Package Marking And Ordering Information

Device	Device Package	Marking
HMS75N65T	TO-247	HMS75N65T



TO-247

Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	$V_{DS}$	650	V
Gate-Source Voltage ( $V_{DS}=0\text{V}$ ) AC ( $f>1\text{ Hz}$ )	$V_{GS}$	$\pm 30$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_D \text{ (DC)}$	75	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_D \text{ (DC)}$	47	A
Pulsed drain current <sup>(Note 1)</sup>	$I_{DM} \text{ (pulse)}$	300	A
Maximum Power Dissipation( $T_c=25^\circ\text{C}$ ) Derate above $25^\circ\text{C}$	$P_D$	510	W
		4.08	$\text{W}/^\circ\text{C}$
Single pulse avalanche energy <sup>(Note 2)</sup>	$E_{AS}$	1936	mJ
Avalanche current <sup>(Note 1)</sup>	$I_{AR}$	28	A
Repetitive Avalanche energy , $t_{AR}$ limited by $T_{jmax}$ (Note 1)	$E_{AR}$	2.5	mJ

Parameter	Symbol	Value	Unit
Drain Source voltage slope, $V_{DS} \leq 480$ V,	$dv/dt$	50	V/ns
Reverse diode $dv/dt$ , $V_{DS} \leq 480$ V, $I_{SD} < I_D$	$dv/dt$	50	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+150	°C

\* limited by maximum junction temperature

**Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	0.245	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	62	°C /W

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>On/off states</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0$ V $I_D=500\mu A$	650			V
Zero Gate Voltage Drain Current( $T_c=25$ °C)	$I_{DSS}$	$V_{DS}=650$ V, $V_{GS}=0$ V			5	μA
Zero Gate Voltage Drain Current( $T_c=125$ °C)	$I_{DSS}$	$V_{DS}=650$ V, $V_{GS}=0$ V			500	μA
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20$ V, $V_{DS}=0$ V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=500\mu A$	2.5	3.5	4.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10$ V, $I_D=38$ A		36	41	mΩ
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=100$ V, $V_{GS}=0$ V, $f=1.0$ MHz		7300	8500	PF
Output Capacitance	$C_{oss}$			252		PF
Reverse Transfer Capacitance	$C_{rss}$			4		PF
Total Gate Charge	$Q_g$	$V_{DS}=480$ V, $I_D=75$ A, $V_{GS}=10$ V		116	135	nC
Gate-Source Charge	$Q_{gs}$			40		nC
Gate-Drain Charge	$Q_{gd}$			30		nC
<b>Switching times</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=380$ V, $I_D=38$ A, $R_G=1.2\Omega$ , $V_{GS}=10$ V		27		nS
Turn-on Rise Time	$t_r$			22		nS
Turn-Off Delay Time	$t_{d(off)}$			118	180	nS
Turn-Off Fall Time	$t_f$			13	30	nS
<b>Source- Drain Diode Characteristics</b>						
Source-drain current(Body Diode)	$I_{SD}$	$T_c=25$ °C		75		A
Pulsed Source-drain current(Body Diode)	$I_{SDM}$			300		A
Forward on voltage	$V_{SD}$	$T_j=25$ °C, $I_{SD}=75$ A, $V_{GS}=0$ V		1.3		V
Reverse Recovery Time	$t_{rr}$	$T_j=25$ °C, $I_F=38$ A, $di/dt=100$ A/μs $V_{DD}=300$ V		230		nS
Reverse Recovery Charge	$Q_{rr}$			3		uC
Peak Reverse Recovery Current	$I_{rrm}$			26		A

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

2.  $T_j=25$  °C,  $V_{DD}=50$  V,  $V_G=10$  V,  $R_G=25\Omega$

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

Figure1. Safe Operating Area

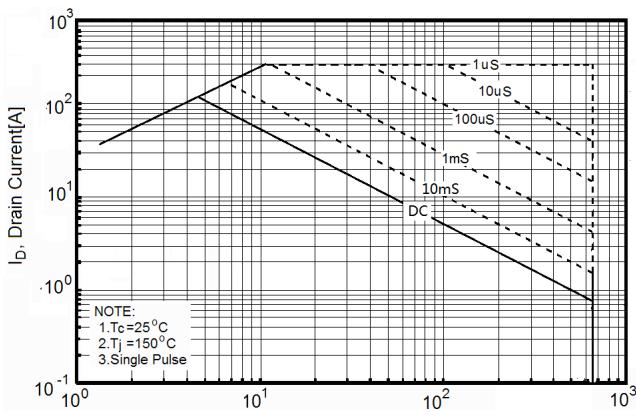


Figure3. Source-Drain Diode Forward Voltage

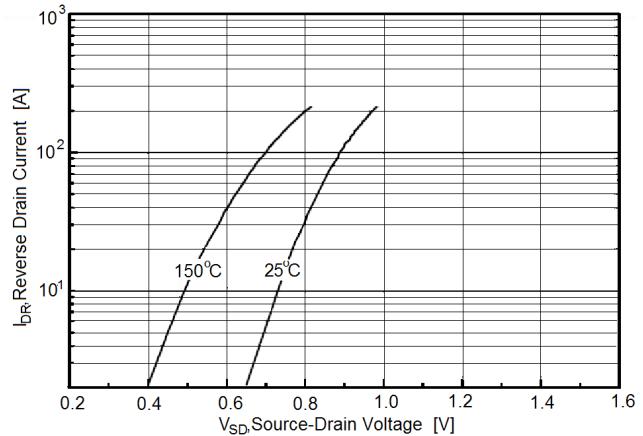


Figure4. Output Characteristics

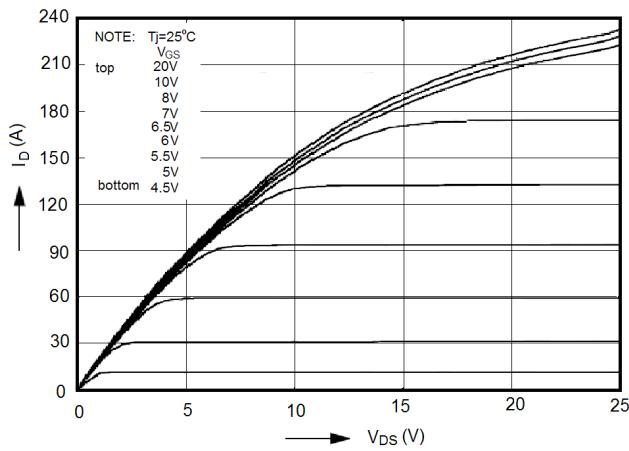


Figure5. Transfer Characteristics

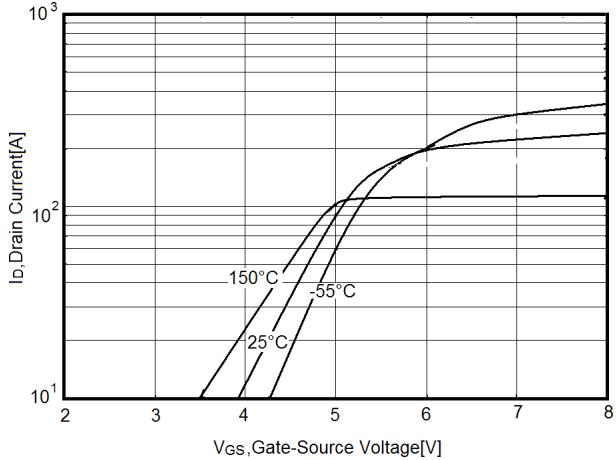


Figure6. Static drain-source on resistance

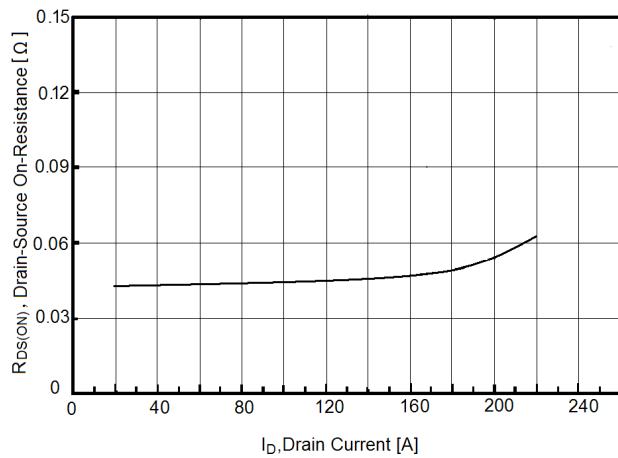


Figure7.  $R_{DS(ON)}$  vs Junction Temperature

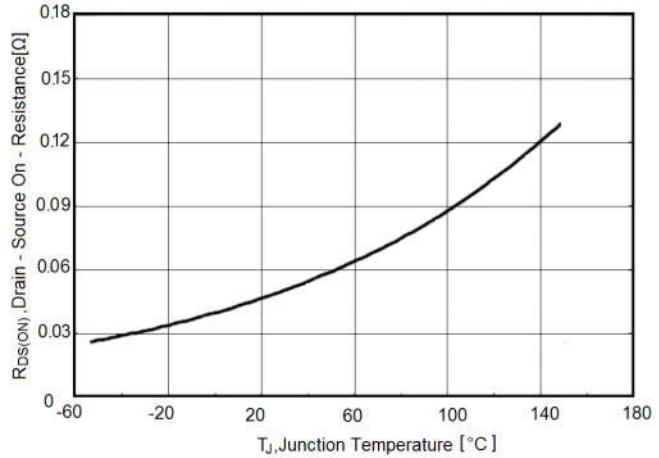


Figure8.  $BV_{DSS}$  vs Junction Temperature

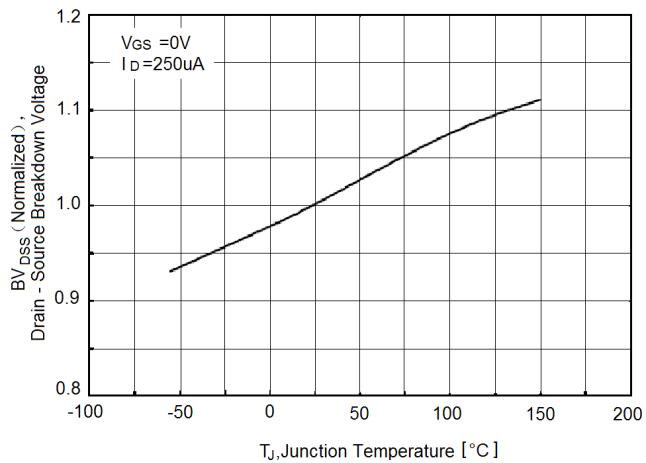
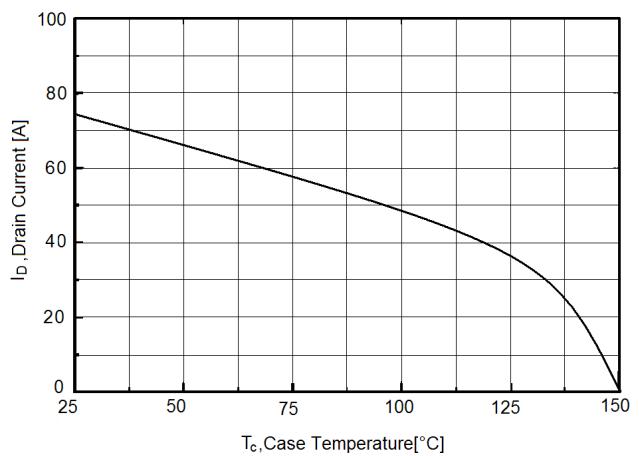
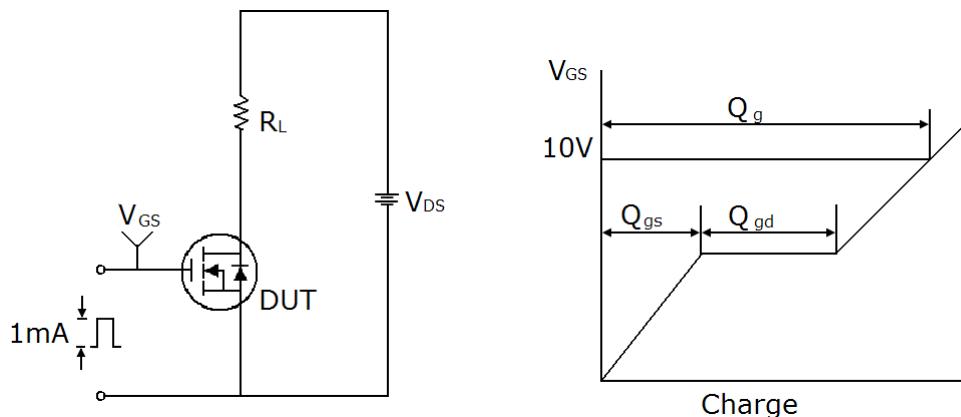


Figure9. Maximum  $I_D$  vs Junction Temperature

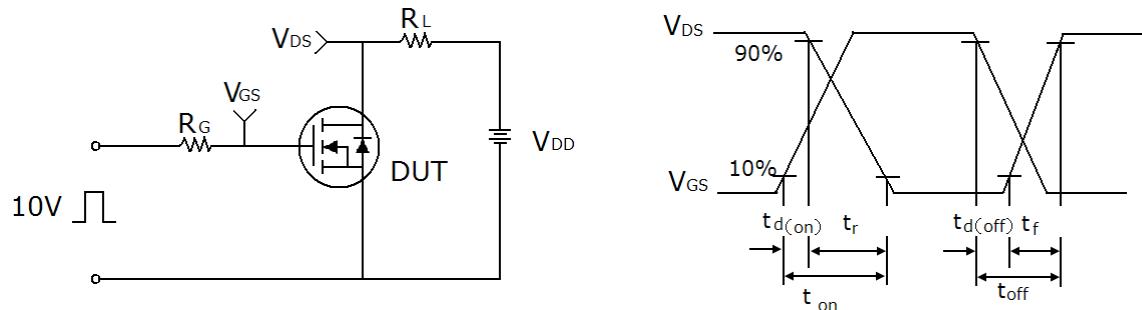


## Test circuit

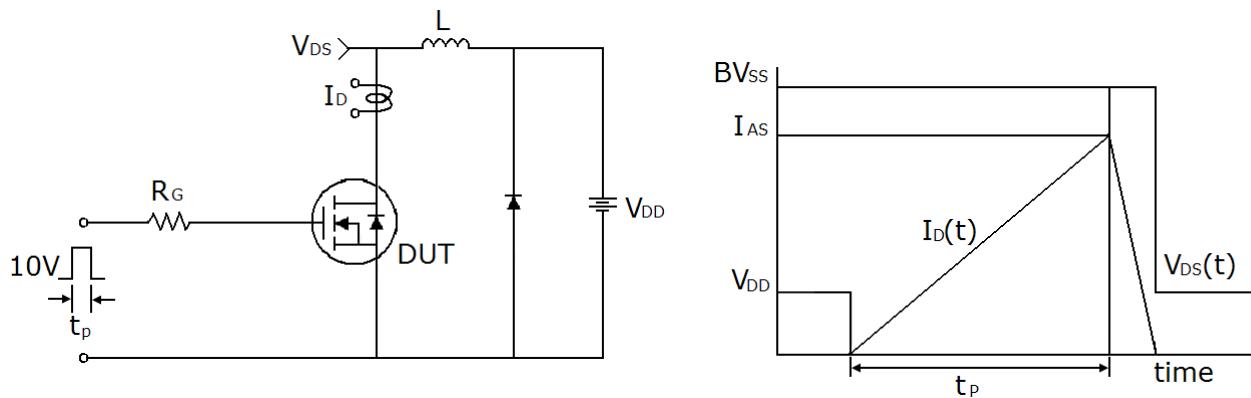
### 1) Gate charge test circuit & Waveform



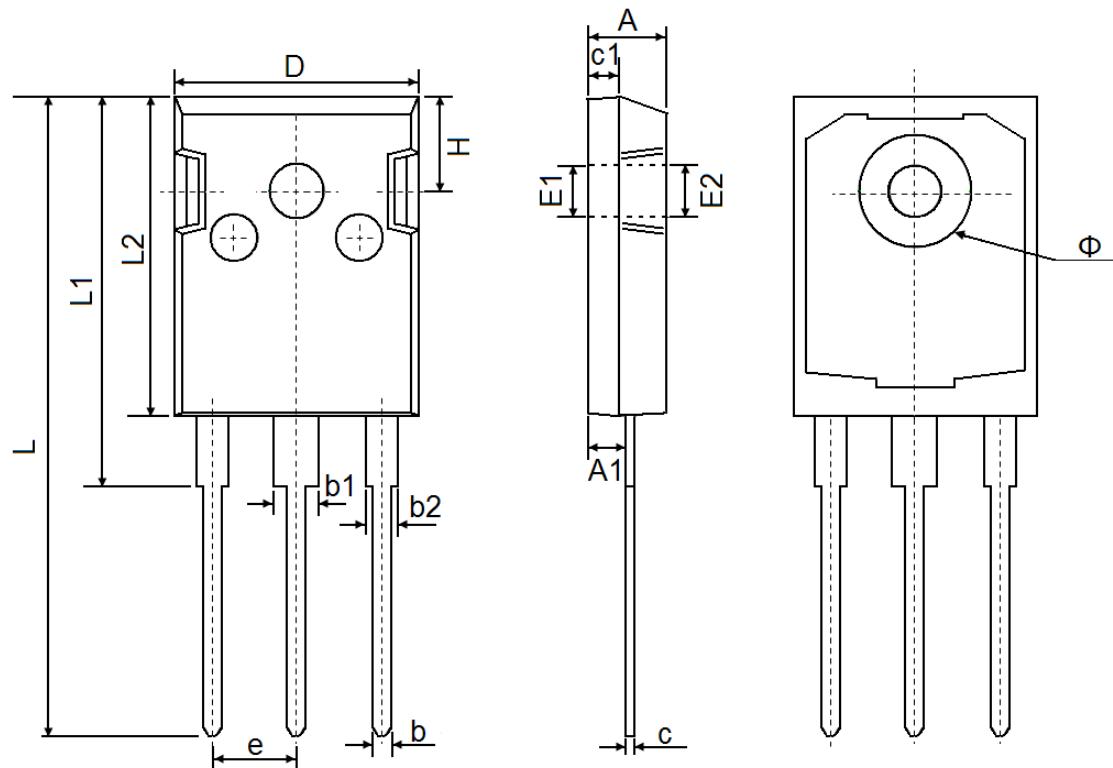
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms



## TO-247 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
b2	1.800	2.200	0.071	0.087
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF		0.138 REF	
E2	3.600 REF		0.142 REF	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP		0.215 TYP	
H	5.980 REF		0.235 REF	